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Local Organizing Committee

Didem Ozevin, University of Illinois at Chicago, USA (Conference Chair)
Hossein Ataei, University of Illinois at Chicago, USA (Conference Co-Chair)
Mehdi Modares, Illinois Institute of Technology, USA (Conference Co-Chair)

Editors

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ISEC-10



THE TENTH INTERNATIONAL STRUCTURAL ENGINEERING AND CONSTRUCTION CONFERENCE

May 20 - 25, 2019 - CHICAGO, UNITED STATES

HOST: University of Illinois at Chicago



CALL FOR PAPERS

INTERDEPENDENCE BETWEEN STRUCTURAL ENGINEERING AND CONSTRUCTION MANAGEMENT

The Tenth International Structural Engineering and Construction Conference (ISEC-10) aims to bring together the state-of-the-art research and their applications in the fields of structural engineering and construction management. The conference will provide a platform to discuss recent technical advancements in the professions of structural engineering and construction. The conference is an excellent opportunity for the exchange of ideas and knowledge, and for discussing future challenges.

Who should attend?

Academics, engineers, entrepreneurs, architects, and other interested persons are invited to attend the conference.

Call for Papers

Authors are invited to submit abstracts of between 125 and 225 words at:
https://www.isec-society.org/ISEC_10/abstractsAndPapers/

Authors must create an account, login, and upload their abstract. Authors of accepted abstracts will be invited to submit full papers for peer review. One author of each accepted paper will be expected to present the paper at the conference. Only accepted papers for which the full registration is paid will be published in the conference proceedings.

Conference Topics

The topics to be covered are in all areas of Structural and Construction Engineering, Air and Water, Architecture and Architectural Engineering, Education and Ethics, Energy, Pipelines, Geotechnical and Foundation Engineering, Project Management, Risk and Safety Management, Sustainability, and others. Please see details at: https://www.isec-society.org/ISEC_10/topics.php

Important Dates

Abstract submission	Jun 15, 2018
Abstract acceptance	Jun 30, 2018
Manuscript submission	Oct 17, 2018
Revised Manuscript submission	Nov 1, 2018
Manuscript acceptance	Nov 15, 2018
Early Bird Registration (necessary for publication of papers)	Jan 26, 2019

Conference Activities and Dates

Evening Welcome Reception	May 20, 2019
Opening Session	May 21, 2019
Conference sessions	May 21 - 22, 2019
Dinner banquet	May 23, 2019
Technical Tour	May 23, 2019
Cultural and Networking Tours	May 24 - 25, 2019

Conference Venue

The conference will be held at the University of Illinois at Chicago (UIC).

About Chicago

Please see details at https://www.isec-society.org/ISEC_10/about.php.

Weather in Chicago

Springtime in Chicago means blooming flowers, and is perhaps the city's wettest season. Thunderstorms are especially prevalent in the spring time. Winter conditions can persist well into April and occasionally into May. Temperatures can vary tremendously in the springtime, but they really start to warm up with May up to around 70°F (21°C).

As with anything related to nature, the above are general guidelines only. It's possible to have cooler or hotter days in the Spring.

Transportation in Chicago

For information about how to get around Chicago, public transportation, transportation to and from the airport, click on the links below:

<https://www.choosechicago.com/plan-your-trip/transportation/>

http://www.encyclopedia.com/places/united-states-and-canada/us-political-geography/chicago#GETTING_AROUND

Accommodation

Information concerning recommended hotels, special booking rates and deadlines will be made available in due time.

Conference Products and Registration Fees

Products	Early Bird Before January 26, 2019	Standard Rates
Regular Registration	\$795	\$895
Student Registration	\$650	\$750
Developing Country Regular Registration	\$695	\$795
Developing Country Student Registration	\$575	\$675
Accompanying Person Registration (AP)	\$325	\$375
A/P Tours	Only for A/Ps. No extra charge	
Cultural Tour 1	\$35	\$35
Cultural Tour 2	\$40	\$40
Technical Tour	\$55	\$55
Dinner Banquet	\$90	\$99
Evening Welcome Reception	\$20	\$20
Exhibitor	\$950	\$1,050
Registration without Paper	\$875	\$975
Publishing without Attending (One Paper)	\$385	\$410
Publishing without Attending (Two Papers)	\$450	\$475
Additional Paper (Beyond Two)	\$250	\$295

Regular, student, and exhibitor registrations include conference lunches, coffee breaks, and conference proceedings. The technical and cultural tours registration is extra for all registrants.

All students will be required to show a valid student ID at the conference registration desk.

Accompanying person (A/P) registration includes lunches, coffee breaks, reception, and A/P tours during the main conference (if held).

Authors (including co-authors) may submit up to TWO manuscripts for one registration fee; for each additional manuscript published an additional fee must be paid.

Please register online at <https://isec-society.org/store/ISEC-10-registration>

Accompanying Person Program

More information in due course...

Exhibits

The Conference will provide an opportunity for companies to display their latest products and services in the field of structural engineering and construction. Those interested in having a display booth should contact the local organizing committee. Visit the Contacts page for contact information.

Technical Tour

Thursday, May 23, 2019 – Chicago Architecture Boat Tour - \$55

More information at https://www.isec-society.org/ISEC_10/techtours.php

Technical Tour is extra for all registrants.

Cultural & Networking Tours

Cultural Tour 1: Friday, 24 May, 2019 – Science and Industry Museum - \$35

Cultural Tour 2: Saturday, 25 May, 2019 – Art Institute of Chicago - \$40

More information at https://www.isec-society.org/ISEC_10/cultural_tours.php

Cultural & Networking Tours are extra for all registrants.

Dress Code

Smart Casual Wear.

Contact Information:

ISEC Society
Email: isec.sec@gmail.com